

# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	$P_PP$	120	W	8/20µs, per Figure 1
Peak Pulse Current	I <sub>PP</sub>	10	Α	8/20µs, per Figure 1
ESD Protection – Contact Discharge	V <sub>ESD_Contact</sub>	±30	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V <sub>ESD_Air</sub>	±30	kV	IEC 61000-4-2 Standard

## **Thermal Characteristics**

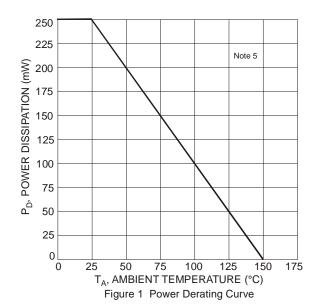
Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	$P_{D}$	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ hetaJA}$	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

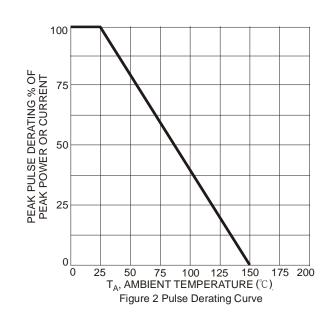
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Standoff Voltage	$V_{RWM}$	_	_	5.5	V	
Channel Leakage Current (Note 6)	I <sub>RM</sub>	_	_	500	nA	$V_{RWM} = 5V$
Breakdown Voltage	$V_{BR}$	6.2	_	_	V	I <sub>R</sub> = 1mA
Clamping Voltage, Positive Transients	V <sub>CL</sub>	_	_	8	V	$I_{PP} = 1A$ , $t_P = 8/20 \mu S$
		_	_	11	V	$I_{PP} = 10A, t_P = 8/20\mu S$
ESD Clamping Voltage, Positive Transient, TLP	V <sub>ESD_CLP</sub>	_	8.75	_	V	$I_{TLP} = 10A, t_P = 100ns$
ESD Clamping Voltage, Negative Transient, TLP	V <sub>ESD_CLN</sub>	_	-2.0	_	V	I <sub>TLP</sub> = -10A, t <sub>P</sub> = 100ns
Differential Resistance	R <sub>DYN</sub>	_	0.15	_	Ω	$I_{TLP}$ = 10A to 20A, $t_P$ = 100ns, I/O to GND
Channel Input Capacitance	C <sub>IN</sub>	_	55	_	pF	V <sub>R</sub> = 0V, f = 1MHz

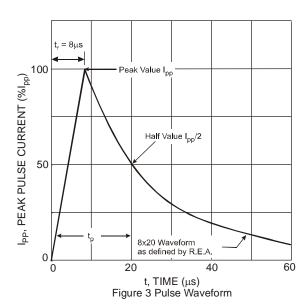
Notes:

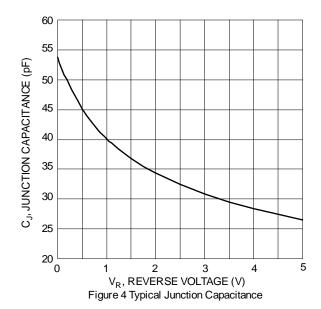
- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc., which can be found on our website at http://www.diodes.com/package-outlines.html.
- 6. Short duration pulse test used to minimize self-heating effect.







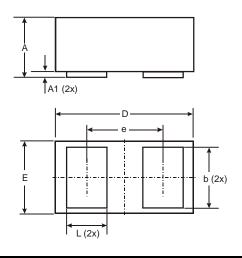




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X3-DFN0603-2

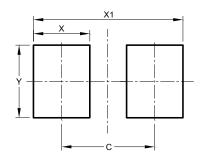


X3-DFN0603-2					
Dim	Min	Max	Тур		
Α	0.27	0.35	0.30		
A1	0.00	0.03	0.02		
b	0.19	0.29	0.24		
D	0.595	0.645	0.62		
Е	0.295	0.345	0.32		
е	-	-	0.355		
L	0.14	0.24	0.19		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X3-DFN0603-2



Dimensions	Value		
Dilliensions	(in mm)		
C	0.380		
Х	0.230		
X1	0.610		
Y	0.300		



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